







## **IF3602** Dual Matched N-Channel JFET

#### **Features**

InterFET N3600L Geometry

Ultra Low Noise: 0.5 nV/VHz Typical

High Gain: 750mS TypicalLow Rds(on): 2.0 Ohms Typical

RoHS Compliant

• SMT, TH, and Bare Die Package options.

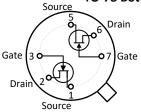
### **Applications**

- · Low-Noise, High Gain Amplifiers
- · Differential Amplifiers

### Description

The -20V InterFET IF3602 JFET is targeted for ultra low noise high gain differential amplifier designs. The IF3602 has a cutoff voltage of less than 2.0V ideal for low voltage applications. The TO-78 package is hermetically sealed and suitable for military applications. Custom specifications, matching, and packaging options are available.

#### **TO-78 Bottom View**





#### **Product Summary**

- 10 date out the same of the						
	Parameters	IF3602 Min	Unit			
BV <sub>GSS</sub>	Gate to Source Breakdown Voltage	-20	V			
I <sub>DSS</sub>	Drain to Source Saturation Current	30	mA			
V <sub>GS(off)</sub>	Gate to Source Cutoff Voltage	-0.35	V			
G <sub>FS</sub>	Forward Transconductance	750 Typical	mS			

### Ordering Information Custom Part and Binning Options Available

Part Number	Description	Case	Packaging		
IF3602T78	Through-Hole	TO-78	Bulk		
IF3602COT *	Chip Orientated Tray (COT Waffle Pack)	СОТ	30/Waffle Pack		
IF3602CFT *	Chip Face-up Tray (CFT Waffle Pack)	CFT	30/Waffle Pack		

<sup>\*</sup> Bare die packaged options are designed for matched specifications but not 100% tested



**Disclaimer:** It is the Buyers responsibility for designing, validating and testing the end application under all field use cases and extreme use conditions. Guaranteeing the application meets required standards, regulatory compliance, and all safety and security requirements is the responsibility of the Buyer. These resources are subject to change without notice.









## **Electrical Characteristics**

Maximum Ratings (@ T<sub>A</sub> = 25°C, Unless otherwise specified)

	Parameters	Value	Unit
$V_{\text{RGS}}$	Reverse Gate Source and Gate Drain Voltage	-20	V
I <sub>FG</sub>	Continuous Forward Gate Current	10	mA
PD	Continuous Device Power Dissipation	300	mW
Р	Power Derating	4	mW/°C
Tı	Operating Junction Temperature	-55 to 125	°C
T <sub>STG</sub>	Storage Temperature	-65 to 200	°C

Static Characteristics (@ TA = 25°C, Unless otherwise specified)

	Parameters	Conditions	Min	Тур	Max	Unit
V <sub>(BR)GSS</sub>	Gate to Source Breakdown Voltage	$V_{DS} = 0V$ , $I_{G} = -1\mu A$	-20			V
I <sub>GSS</sub>	Gate to Source Reverse Current	$V_{GS} = -10V, V_{DS} = 0V$			-0.1	nA
V <sub>GS(OFF)</sub>	Gate to Source Cutoff Voltage	$V_{DS} = 10V, I_D = 0.5nA$	-0.35		-2.0	V
I <sub>DSS</sub>	Drain to Source Saturation Current	$V_{GS} = 0V$ , $V_{DS} = 10V$ (Pulsed)	30	300		mA

**Dynamic Characteristics** (@ TA = 25°C, Unless otherwise specified)

	Parameters	Conditions	Min	Тур	Max	Unit
G <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1kHz		750		mS
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 0V, V <sub>GS</sub> = -4V, f = 1MHz		300		pF
Crss	Reverse Transfer Capacitance	V <sub>DS</sub> = 0V, V <sub>GS</sub> = -4V, f = 1MHz		200		pF
e <sub>n</sub>	Equivalent Circuit Input Noise Voltage	V <sub>DS</sub> = 3V, I <sub>D</sub> = 5mA, f = 100Hz		0.5		nV/√Hz
V <sub>GS1</sub> – V <sub>GS2</sub>	Differential Gate Source Voltage	V <sub>DS</sub> = 10V, I <sub>D</sub> = 500pA			100	mV

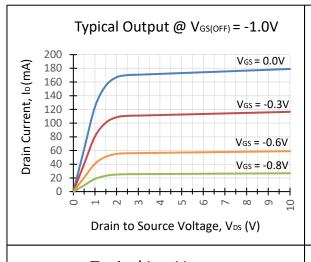


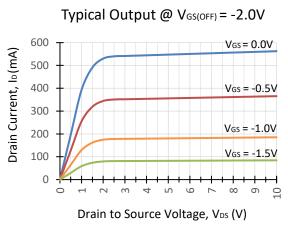


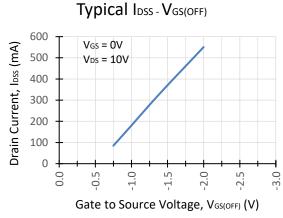


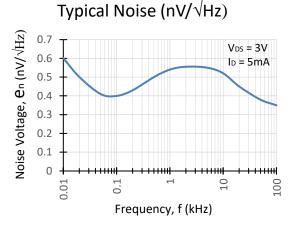


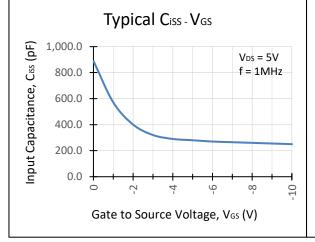
# **Typical IF3602 Characteristics**

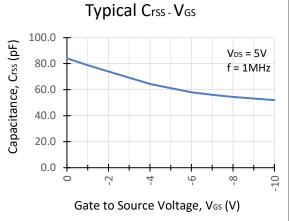














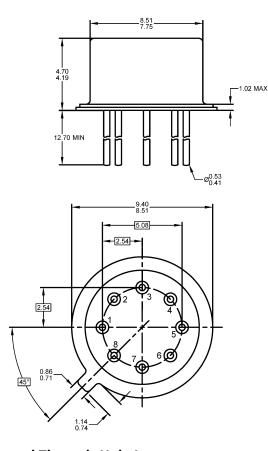






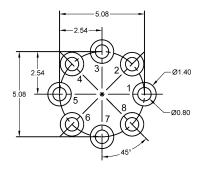
# **TO-78 Mechanical and Layout Data**

## **Package Outline Data**



- 1. All linear dimensions are in millimeters.
- Eight leaded device. Not all leads are shown in drawing views.
- 3. Some package configurations will not populate pin 8 and/or pin 7.
- 4. Package weight approximately 0.44 grams
- Bulk product is shipped in standard ESD shipping material
- 6. Refer to JEDEC standards for additional information.

# **Suggested Through-Hole Layout**



- 1. All linear dimensions are in millimeters.
- 2. The suggested land pattern dimensions have been provided as a straight lead reference only. A more robust pattern may be desired for wave soldering and/or bent lead configurations.